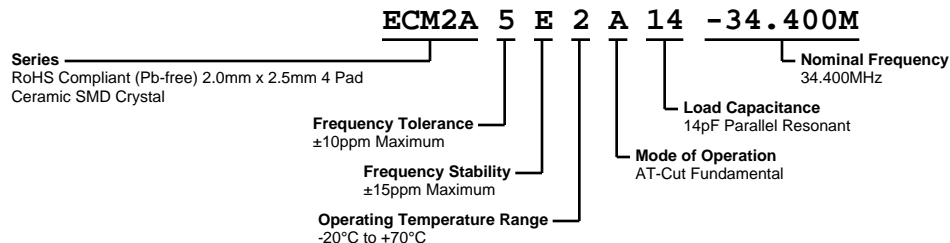


ECM2A5E2A14-34.400M



ECLIPTEK[®]
CORPORATION



ELECTRICAL SPECIFICATIONS

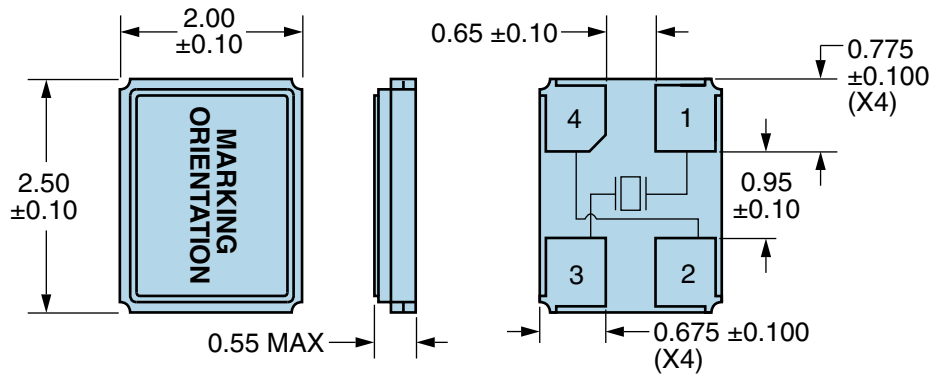
Nominal Frequency	34.400MHz
Frequency Tolerance	±10ppm Maximum
Frequency Stability	±15ppm Maximum
Aging at 25°C	±3ppm/year Maximum
Operating Temperature Range	-20°C to +70°C
Load Capacitance	14pF Parallel Resonant
Shunt Capacitance (C0)	5pF Maximum
Equivalent Series Resistance	60 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100µWatts Maximum
Spurious Response	-3dB Minimum; Fo to Fo +5000ppm
Storage Temperature Range	-40°C to +90°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	34.4
2	YZZ Y=Last Digit of Year ZZ=Week of the Year

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_s MAX to T_L (Ramp-up Rate)	3°C/second Maximum
Preheat	
- Temperature Minimum (T_s MIN)	150°C
- Temperature Typical (T_s TYP)	175°C
- Temperature Maximum (T_s MAX)	200°C
- Time (t_s MIN)	60 - 180 Seconds
Ramp-up Rate (T_L to T_p)	3°C/second Maximum
Time Maintained Above:	
- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds
Peak Temperature (T_p)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T_p Target)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 seconds
Ramp-down Rate	6°C/second Maximum
Time 25°C to Peak Temperature (t)	8 minutes Maximum
Moisture Sensitivity Level	Level 1

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

$T_S\ MAX$ to T_L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum ($T_S\ MIN$)	N/A
- Temperature Typical ($T_S\ TYP$)	150°C
- Temperature Maximum ($T_S\ MAX$)	N/A
- Time ($t_s\ MIN$)	60 - 120 Seconds
Ramp-up Rate (T_L to T_P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T_L)	150°C
- Time (t_L)	200 Seconds Maximum
Peak Temperature (T_P)	240°C Maximum
Target Peak Temperature ($T_P\ Target$)	240°C Maximum 1 Time / 230°C Maximum 2 Times
Time within 5°C of actual peak (t_p)	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.